MJ11021(PNP)
MJ11022 (NPN)

Complementary Darlington Silicon Power Transistors

Complementary Darlington Silicon Power Transistors are designed for use as general purpose amplifiers, low frequency switching and motor control applications.

Features

- High dc Current Gain @ 10 Adc − h_{FE} = 400 Min (All Types)
- Collector−Emitter Sustaining Voltage
  $V_{CEO(sus)}$ = 250 Vdc (Min) − MJ11022, 21
- Low Collector−Emitter Saturation
  $V_{CE(sat)}$ = 1.0 V (Typ) @ I_C = 5.0 A
  = 1.8 V (Typ) @ I_C = 10 A
- 100% SOA Tested @ V_{CE} = 44 V
  I_C = 4.0 A
  t = 250 ms
- Pb−Free Packages are Available*

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Collector−Emitter Voltage	V_{CEO}	250	Vdc
Collector−Base Voltage	V_{CBO}	250	Vdc
Emitter−Base Voltage	V_{EBO}	50	Vdc
Collector Current − Continuous − Peak (Note 1)	I_C	15 30	Adc
Base Current	I_B	0.5	Adc
Total Power Dissipation @ T_C = 25°C Derate Above 25°C	P_D	175 1.16	W W/°C
Operating and Storage Junction Temperature Range	T_J, T_{stg}	−65 to +175 − 65 to +200	°C

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction−to−Case	$R_{\theta JC}$	0.86	°C/W

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. Pulse Test: Pulse Width = 5 ms, Duty Cycle ≤ 10%.

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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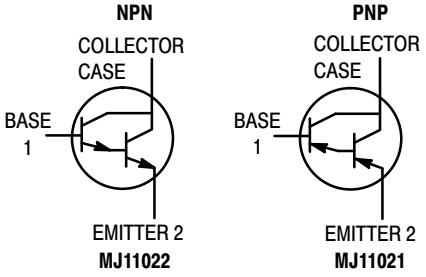
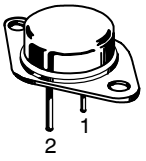
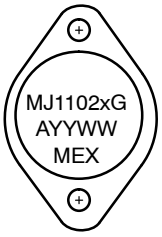
15 AMPERE COMPLEMENTARY DARLINGTON POWER TRANSISTORS 250 VOLTS, 175 WATTS





TO−204 (TO−3)
CASE 1−07
STYLE 1

MARKING DIAGRAM



MJ1102x = Device Code
x = 1 or 2
G = Pb−Free Package
A = Location Code
YY = Year
WW = Work Week
MEX = Country of Orgin

ORDERING INFORMATION

Device	Package	Shipping
MJ11021	TO−3	100 Units/Tray
MJ11021G	TO−3 (Pb−Free)	100 Units/Tray
MJ11022	TO−3	100 Units/Tray
MJ11022G	TO−3 (Pb−Free)	100 Units/Tray

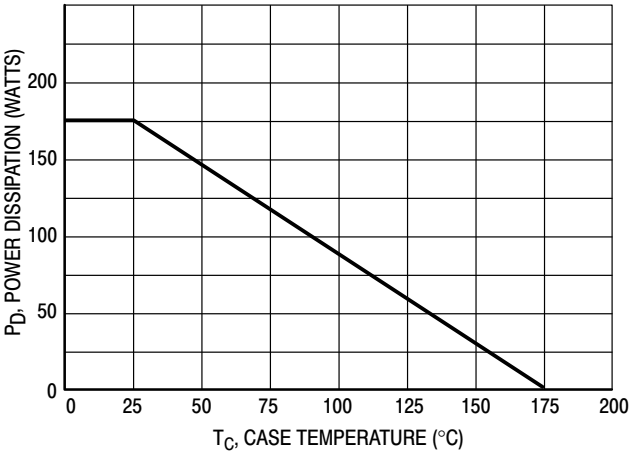
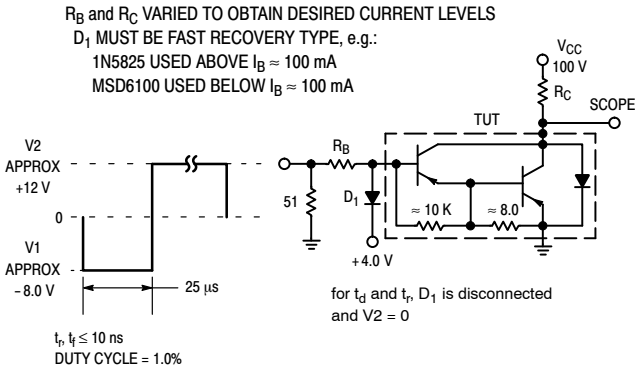


Figure 1. Power Derating



For NPN test circuit reverse diode and voltage polarities.

Figure 2. Switching Times Test Circuit

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector−Emitter Sustaining Voltage (Note 1) (I_C = 0.1 Adc, I_B = 0) MJ11021, MJ11022	$V_{CEO(sus)}$	250	–	Vdc
Collector Cutoff Current (V_{CE} = 125, I_B = 0) MJ11021, MJ11022	I_{CEO}	–	1.0	mAdc
Collector Cutoff Current (V_{CE} = Rated V_{CB}, $V_{BE(off)}$ = 1.5 Vdc) (V_{CE} = Rated V_{CB}, $V_{BE(off)}$ = 1.5 Vdc, T_J = 150°C)	I_{CEV}	– –	0.5 5.0	mAdc
Emitter Cutoff Current (V_{BE} = 5.0 Vdc, I_C = 0)	I_{EBO}	–	2.0	mAdc
ON CHARACTERISTICS (Note 1)				
DC Current Gain (I_C = 10 Adc, V_{CE} = 5.0 Vdc) (I_C = 15 Adc, V_{CE} = 5.0 Vdc)	h_{FE}	400 100	15,000 –	–
Collector−Emitter Saturation Voltage (I_C = 10 Adc, I_B = 100 mA) (I_C = 15 Adc, I_B = 150 mA)	$V_{CE(sat)}$	– –	2.0 3.4	Vdc
Base−Emitter On Voltage I_C = 10 A, V_{CE} = 5.0 Vdc)	$V_{BE(on)}$	–	2.8	Vdc
Base−Emitter Saturation Voltage (I_C = 15 Adc, I_B = 150 mA)	$V_{BE(sat)}$	–	3.8	Vdc
DYNAMIC CHARACTERISTICS				
Current−Gain Bandwidth Product (I_C = 10 Adc, V_{CE} = 3.0 Vdc, f = 1.0 MHz)	$[h_{fe}]$	3.0	–	Mhz
Output Capacitance (V_{CB} = 10 Vdc, I_E = 0, f = 0.1 MHz) MJ11022 MJ11021	C_{ob}	– –	400 600	pF
Small−Signal Current Gain (I_C = 10 Adc, V_{CE} = 3.0 Vdc, f = 1.0 kHz)	h_{fe}	75	–	–

SWITCHING CHARACTERISTICS

Characteristic		Symbol	Typical NPN	Typical PNP	Unit
Delay Time	(V_{CC} = 100 V, I_C = 10 A, I_B = 100 mA $V_{BE(off)}$ = 50 V) (See Figure 2)	t_d	150	75	ns
Rise Time		t_r	1.2	0.5	μs
Storage Time		t_s	4.4	2.7	μs
Fall Time		t_f	10.0	2.5	μs

1. Pulsed Test: Pulse Width = 300 μs, Duty Cycle ≤ 2%.

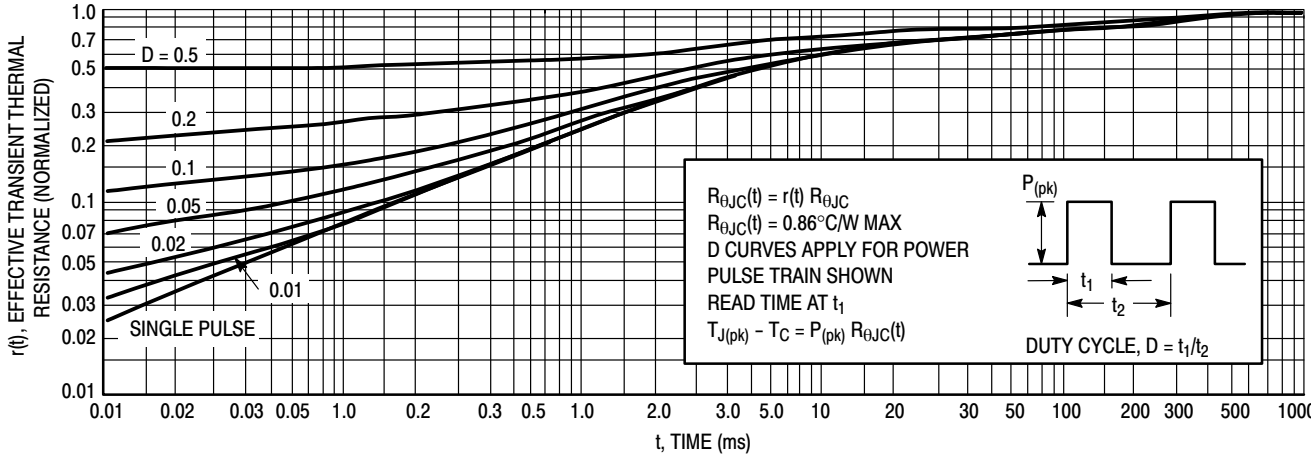


Figure 3. Thermal Response

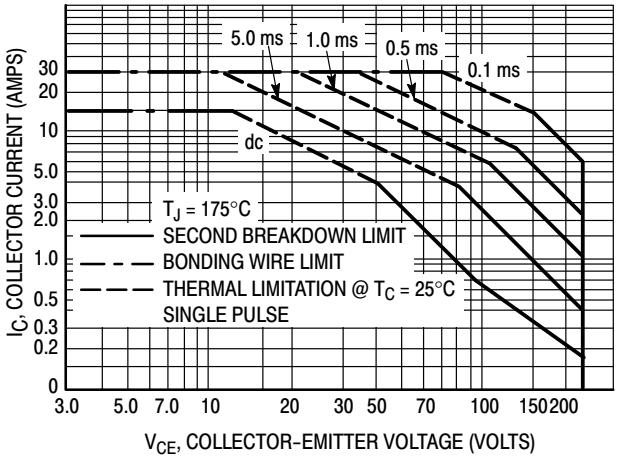


Figure 4. Maximum Rated Forward Bias Safe Operating Area (FBSOA)

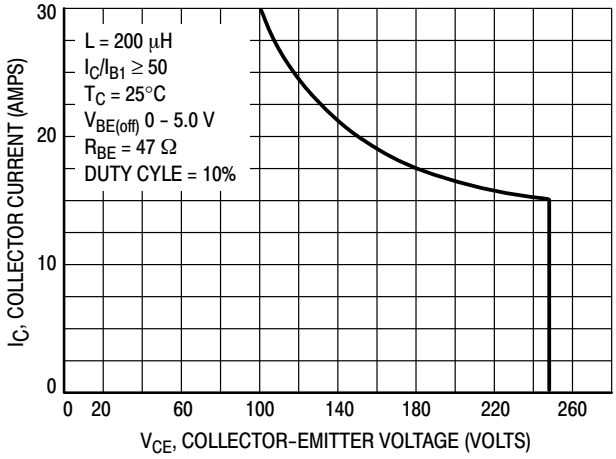


Figure 5. Maximum RBSOA, Reverse Bias Safe Operating Area

FORWARD BIAS

There are two limitations on the power handling ability of a transistor average junction temperature and second breakdown. Safe operating area curves indicate $I_C - V_{CE}$ limits of the transistor that must be observed for reliable operation, i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 4 is based on $T_{J(pk)} = 175°C$, T_C is variable dependIng on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided $T_{J(pk)} \leq 175°C$. $T_{J(pk)}$ may be calculated from the data in Figure 3. At high case temperatures thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

REVERSE BIAS

For inductive loads, high voltage and high current must be sustained simultaneously during turn−off, in most cases, with the base to emitter junction reverse biased. Under these conditions the collector voltage must be hold to a safe level at or below a specific value of collector current. This can be accomplished by several means such as active clamping, RC snubbing, load line shaping, etc. The safe level for these devices is specified as Reverse Bias Safe Operating Area and represents the voltage−current conditions during reverse biased turn−off. This rating is verified under clamped conditions so that the device is never subjected to an avalanche mode. Figure 5 gives ROSOA characteristics.

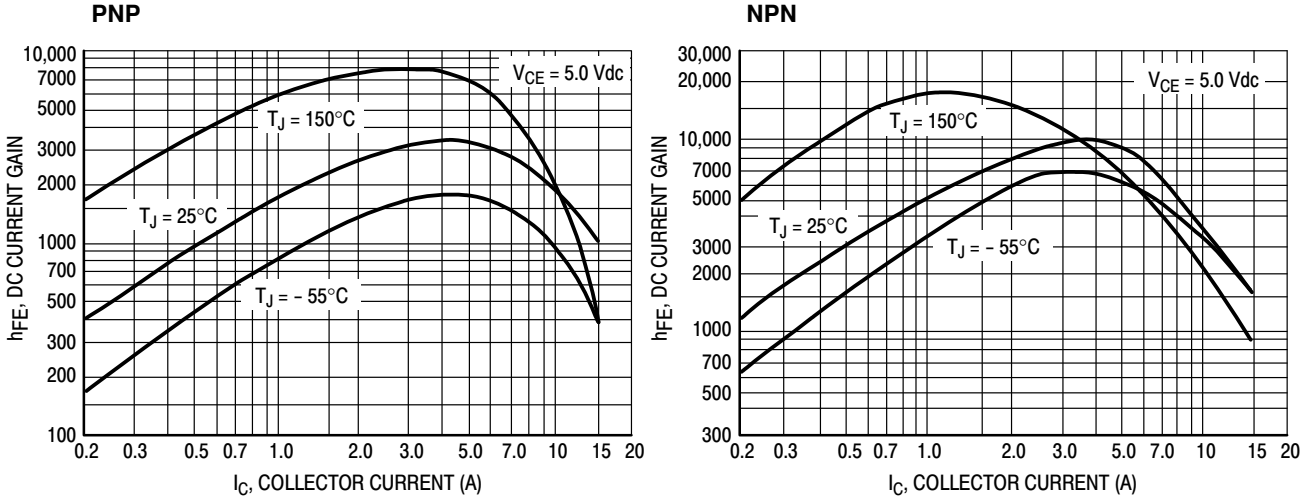


Figure 6. DC Current Gain

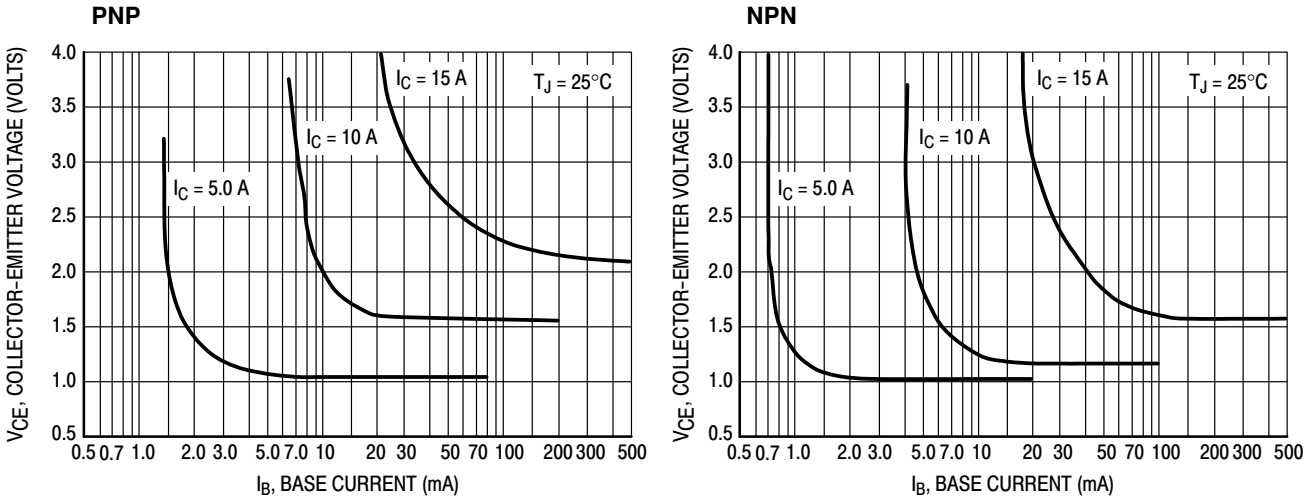


Figure 7. Collector Saturation Region

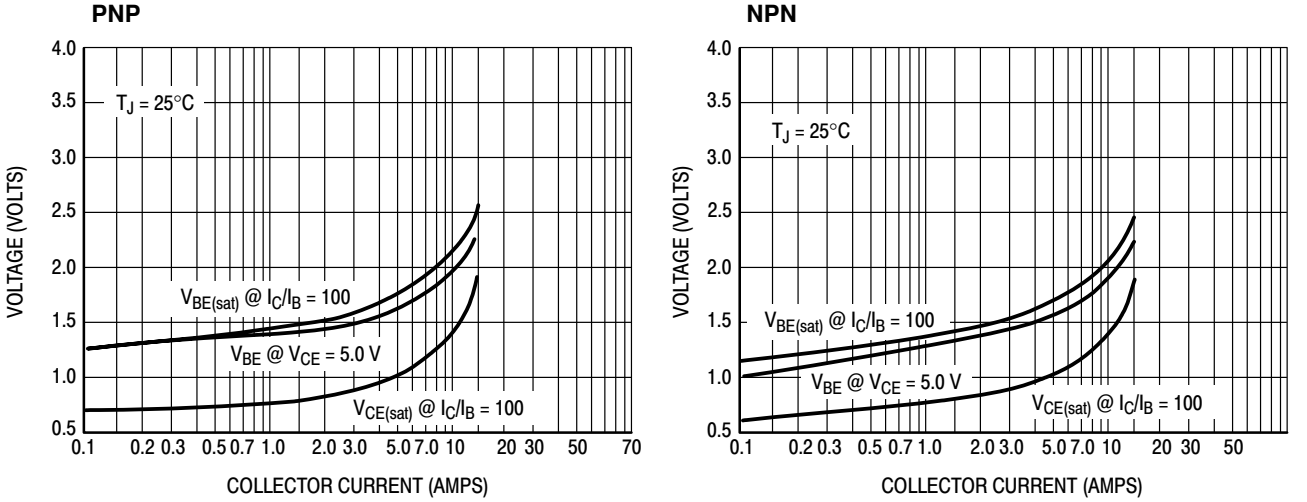
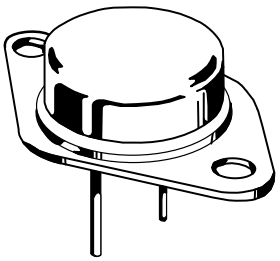


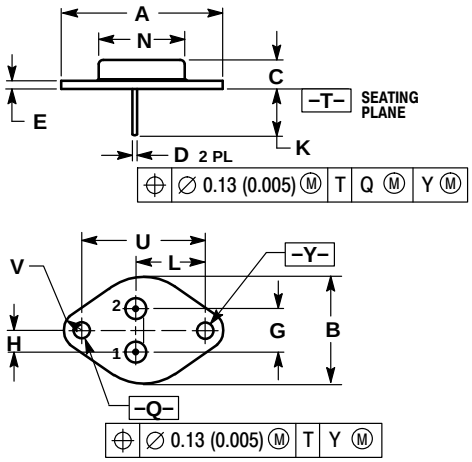
Figure 8. “On” Voltages



SCALE 1:1

TO−204 (TO−3)
CASE 1−07
ISSUE Z

DATE 05/18/1988



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. ALL RULES AND NOTES ASSOCIATED WITH REFERENCED TO−204AA OUTLINE SHALL APPLY.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	1.550 REF		39.37 REF	
B	---	1.050	---	26.67
C	0.250	0.335	6.35	8.51
D	0.038	0.043	0.97	1.09
E	0.055	0.070	1.40	1.77
G	0.430 BSC		10.92 BSC	
H	0.215 BSC		5.46 BSC	
K	0.440	0.480	11.18	12.19
L	0.665 BSC		16.89 BSC	
N	---	0.830	---	21.08
Q	0.151	0.165	3.84	4.19
U	1.187 BSC		30.15 BSC	
V	0.131	0.188	3.33	4.77

STYLE 1:
PIN 1. BASE
2. EMITTER
CASE: COLLECTOR

STYLE 2:
PIN 1. BASE
2. COLLECTOR
CASE: EMITTER

STYLE 3:
PIN 1. GATE
2. SOURCE
CASE: DRAIN

STYLE 4:
PIN 1. GROUND
2. INPUT
CASE: OUTPUT

STYLE 5:
PIN 1. CATHODE
2. EXTERNAL TRIP/DELAY
CASE: ANODE

STYLE 6:
PIN 1. GATE
2. EMITTER
CASE: COLLECTOR

STYLE 7:
PIN 1. ANODE
2. OPEN
CASE: CATHODE

STYLE 8:
PIN 1. CATHODE #1
2. CATHODE #2
CASE: ANODE

STYLE 9:
PIN 1. ANODE #1
2. ANODE #2
CASE: CATHODE

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